

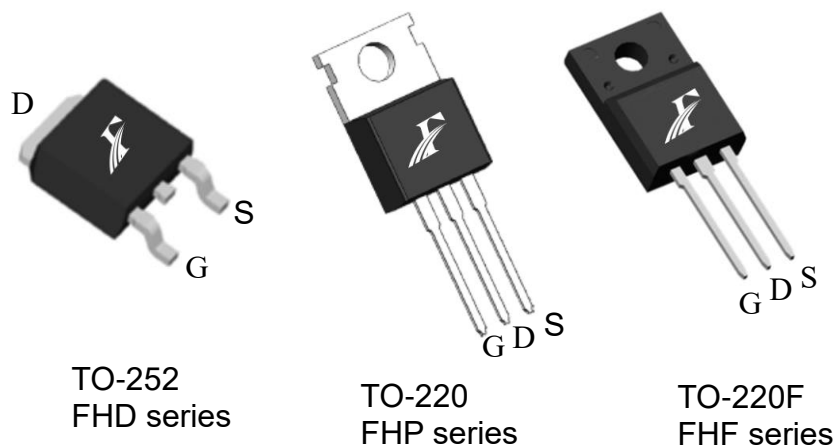
主要参数 MAIN CHARACTERISTICS

ID	5A
VDSS	500 V
Rdson-typ (@Vgs=10V)	1.51Ω
Qg-typ	16.8nC

用途 APPLICATIONS

高频开关电源	High efficiency switch mode power supplies
电机驱动	Motor Drive
逆变电源	Power management for inverter systems

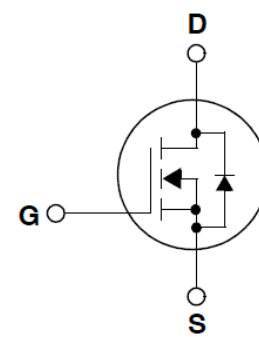
封装形式 Package



产品特性 FEATURES

低栅极电荷	Low gate charge
低 Crss (典型值 2.45pF)	Low Crss (typical 2.45pF)
开关速度快	Fast switching
100%经过雪崩测试	100% avalanche tested
100%经过热阻测试	100% DVDS tested
100%经过 Rg 测试	100% Rg tested
高抗 dv/dt 能力	Improved dv/dt capability
RoHS 产品	RoHS product

等效电路 Equivalent Circuit



绝对最大额定值 ABSOLUTE RATINGS (Tc25°C)

项目 Parameter	符号 Symbol	数值 Value		单位 Unit
		FHP/D830C	FHF830C	
最高漏极-源极直流电压 Drain-Source Voltage	V _{DS}	500		V
连续漏极电流* Drain Current -continuous *	I _D (T _C =25°C)	5		A
	I _D (T _C =100°C)	3.5		A
最大脉冲漏极电流 (注 1) Drain Current – pulse (note 1)	I _{DM}	20		A
最高栅源电压 Gate-Source Voltage	V _{GS}	±30		V
单脉冲雪崩能量 (注 2) Single Pulsed Avalanche Energy (note 2)	E _{AS}	101.25		mJ
雪崩电流 (注 1) Avalanche Current (note 1)	I _{AS}	4.5		A
重复雪崩能量 (注 1) Repetitive Avalanche Current (note 1)	E _{AR}	15		mJ
二极管反向恢复最大电压变化速率 (注 3) Peak Diode Recovery dv/dt (note 3)	dv/dt	5.0		V/ns
耗散功率 Power Dissipation	P _D (T _C =25°C)	78	30	W
	-Derate above 25°C	0.62	0.24	W/°C
最高结温及存储温度 Operating and Storage Temperature Range	T _J , T _{STG}	-55~+150		°C
引线最高焊接温度 Maximum Lead Temperature for Soldering Purposes	T _L	300		°C

*漏极电流由最高结温限制

*Drain current limited by maximum junction temperature

电特性 ELECTRICAL CHARACTERISTICS

项目 Parameter	符号 Symbol	测试条件 Tests conditions	最小 Min	典型 Typ	最大 Max	单位 Units
关态特性 Off –Characteristics						
漏－源击穿电压 Drain-Source Voltage	BV _{DSS}	I _D =250μA, V _{GS} =0V	500	-	-	V
击穿电压温度特性 Breakdown Voltage Temperature Coefficient	ΔBV _{DSS} /Δ T _J	I _D =250μA, referenced to 25℃	-	0.5	-	V/℃
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =500V, V _{GS} =0V, T _C =25℃	-	-	1	μA
		V _{DS} =400V, T _C =125℃	-	-	100	μA
栅极体漏电流 Gate-body leakage current	I _{GSS} (F/R)	V _{DS} =0V, V _{GS} =±30V	-	-	±100	nA
通态特性 On-Characteristics						
阈值电压 Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	2.0	3.0	4.0	V
静态导通电阻 Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V , I _D =2.5A	-	1.51	1.60	Ω
正向跨导 Forward Transconductance	g _{fs}	V _{DS} = 15V, I _D =2.5A (note 4)	-	3.5	-	S
动态特性 Dynamic Characteristics						
栅电阻 Gate Resistance	R _g	f=1.0MHz, V _{DS} OPEN	-	2.0	-	Ω
输入电容 Input capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	674	-	pF
输出电容 Output capacitance	C _{oss}		-	65	-	
反向传输电容 Reverse transfer capacitance	C _{rss}		-	2.45	-	
开关特性 Switching Characteristics						
延迟时间 Turn-On delay time	t _{d(on)}	V _{DS} =250V, I _D =5A, R _G =5Ω V _{GS} =10V (note 4, 5)	-	13	-	ns
上升时间 Turn-On rise time	t _r		-	45	-	ns
延迟时间 Turn-Off delay time	t _{d(off)}		-	50	-	ns
下降时间 Turn-Off Fall time	t _f		-	49	-	ns
栅极电荷总量 Total Gate Charge	Q _g	V _{DS} =400V , I _D =5A , V _{GS} =10V (note 4, 5)	-	16.8	-	nC
栅－源电荷 Gate-Source charge	Q _{gs}		-	5.5	-	nC
栅－漏电荷 Gate-Drain charge	Q _{gd}		-	4.3	-	nC
漏－源二极管特性及最大额定值 Drain-Source Diode Characteristics and Maximum Ratings						
正向最大连续电流 Maximum Continuous Drain -Source Diode Forward Current	I _S		-	-	5	A
正向最大脉冲电流 Maximum Pulsed Drain-Source Diode Forward Current	I _{SM}		-	-	20	A
正向压降 Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =5A	-	-	1.2	V
反向恢复时间 Reverse recovery time	t _{rr}	V _{GS} =0V, I _S =5A ,dI _F /dt=100A/μs (note 4)	-	264	-	ns
反向恢复电荷 Reverse recovery charge	Q _{rr}		-	1.95	-	μC

热特性 THERMAL CHARACTERISTIC

项目 Parameter	符号 Symbol	FHP/D830C	FHF830C	单位 Unit
结到管壳的热阻 Thermal Resistance, Junction to Case	Rth(j-c)	1.60	4.17	°C/W
结到环境的热阻 Thermal Resistance, Junction to Ambient	Rth(j-A)	60	62.5	°C/W

- 注释：
- 1: 脉冲宽度由最高结温限制
 - 2: L=10mH, IAS=4.5A, VDD=50V, RG=25 Ω,起始结温 TJ=25℃
 - 3: ISD ≤5A,di/dt ≤100A/μs,VDD≤BVDSS,起始结温 TJ=25℃
 - 4: 脉冲测试：脉冲宽度 ≤300μs,占空比≤2%
 - 5: 基本与工作温度无关

- Notes:
- 1: Pulse width limited by maximum junction temperature
 - 2: L=10mH, IAS=4.5A, VDD=50V, RG=25 Ω,Starting TJ=25℃
 - 3: ISD ≤5A,di/dt ≤100A/μs,VDD≤BVDSS, Starting TJ=25℃
 - 4: Pulse Test: Pulse Width ≤300μs,Duty Cycle≤2%
 - 5: Essentially independent of operating temperature

特性曲线 Typical Characteristics

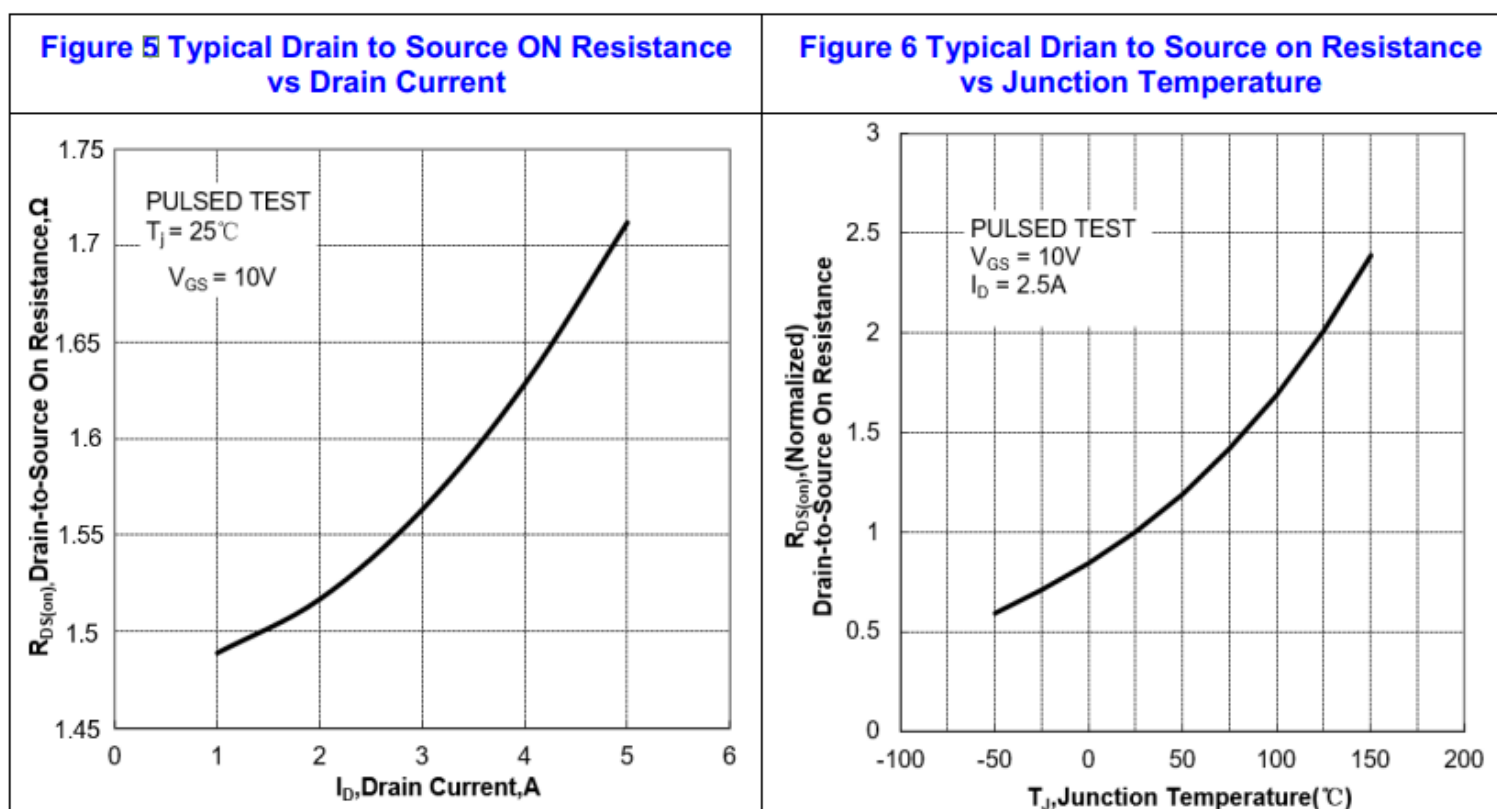
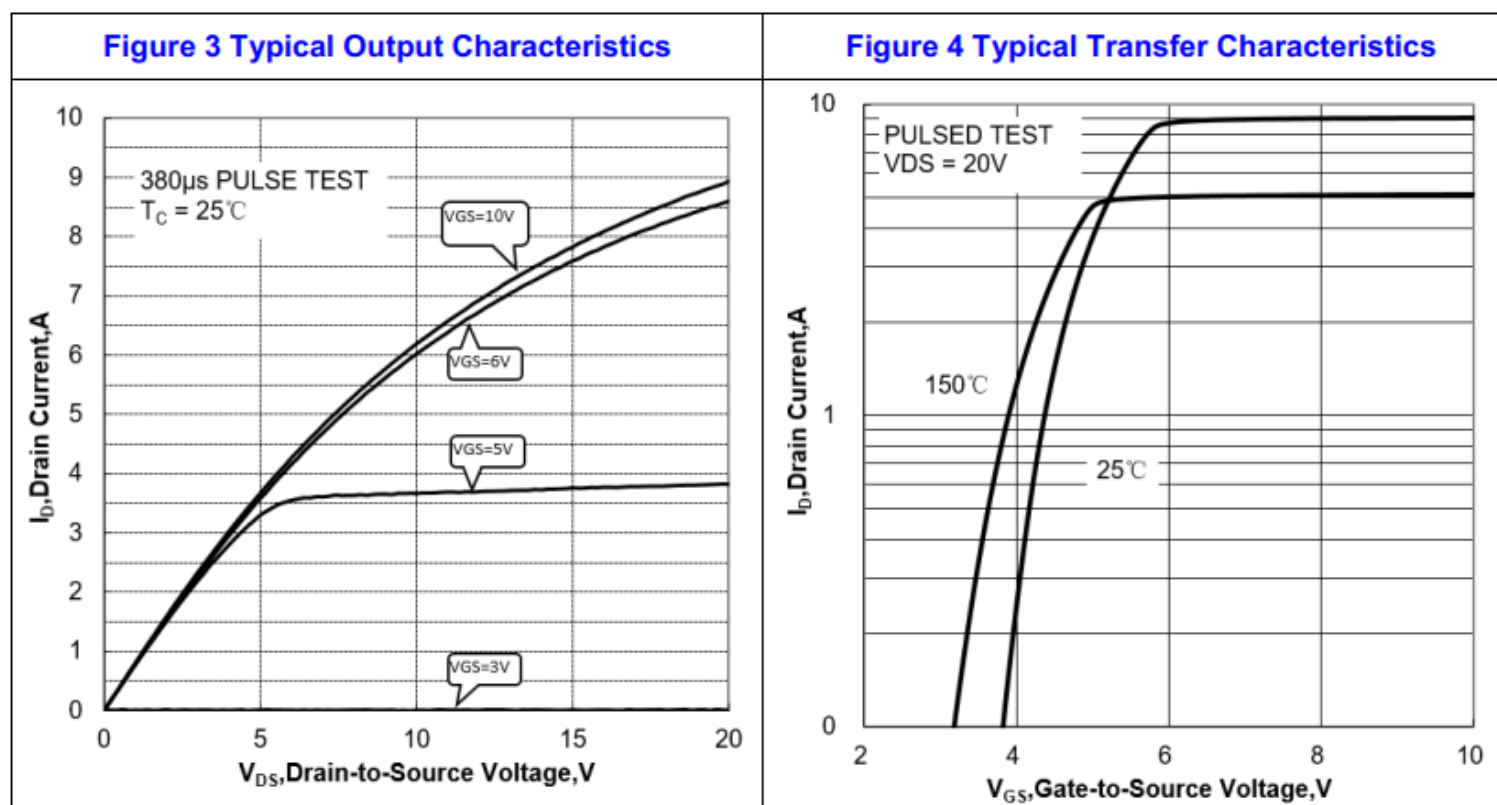
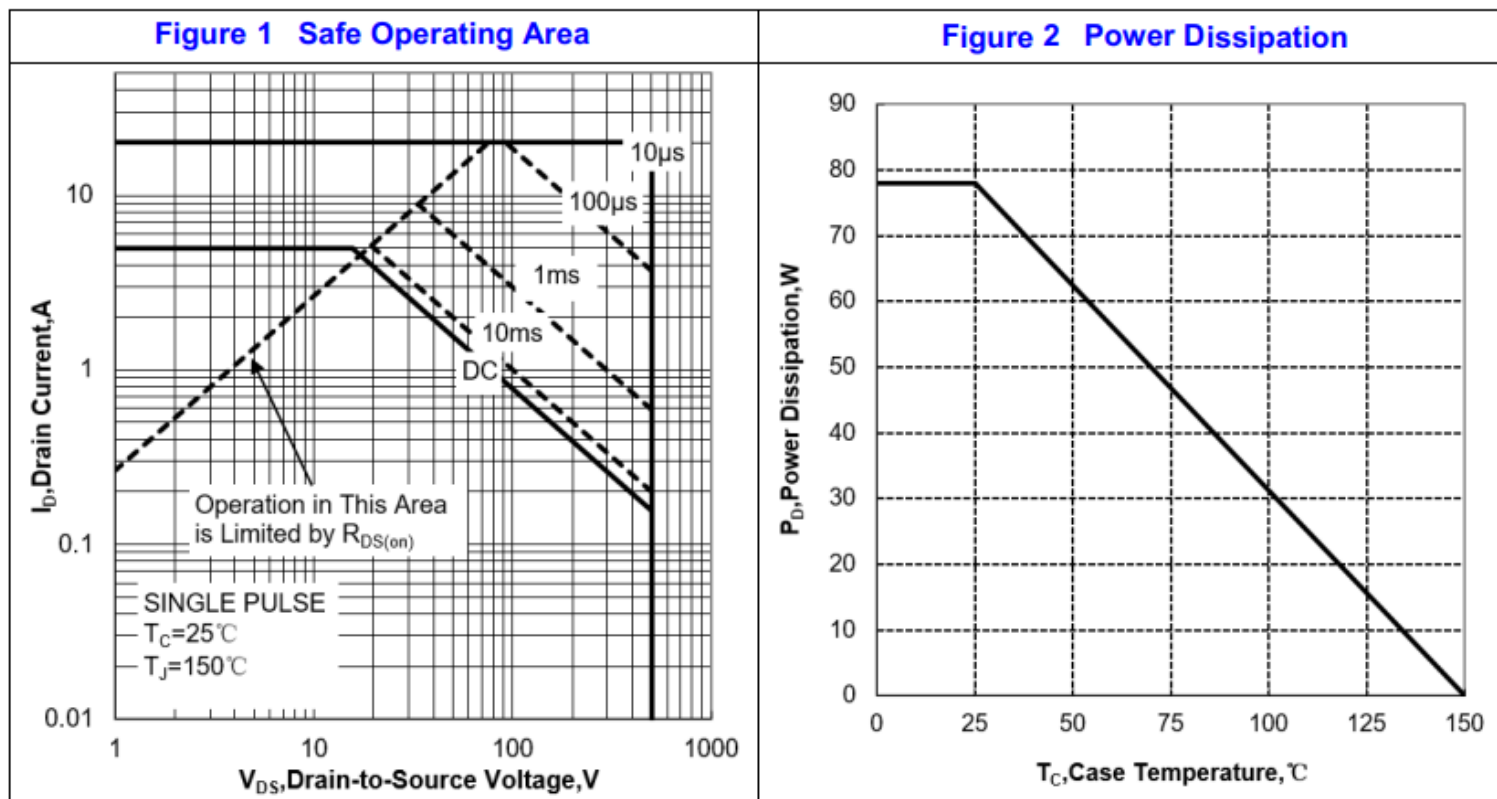


Figure 7 Typical Theshold Voltage vs Junction Temperature

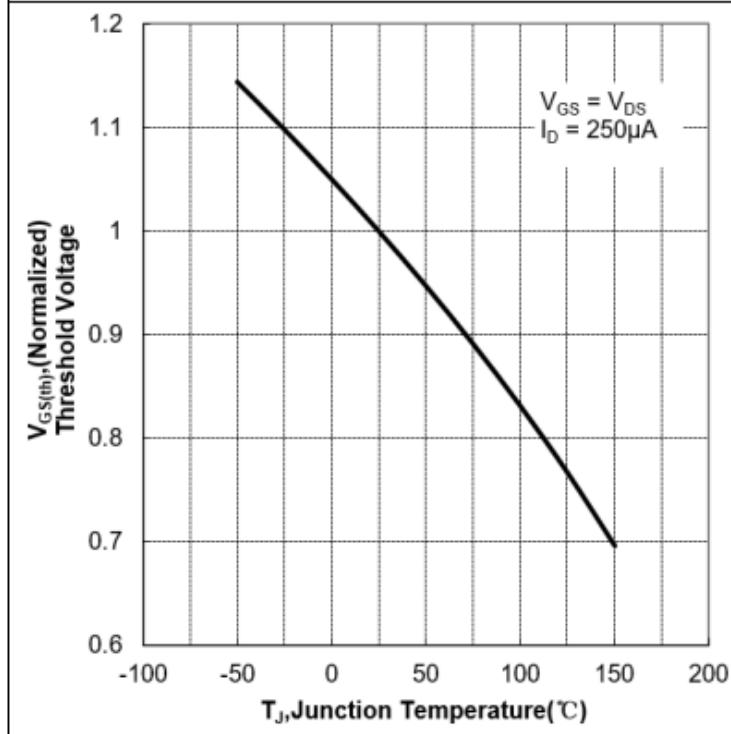


Figure 8 Typical Breakdown Voltage vs Junction Temperature

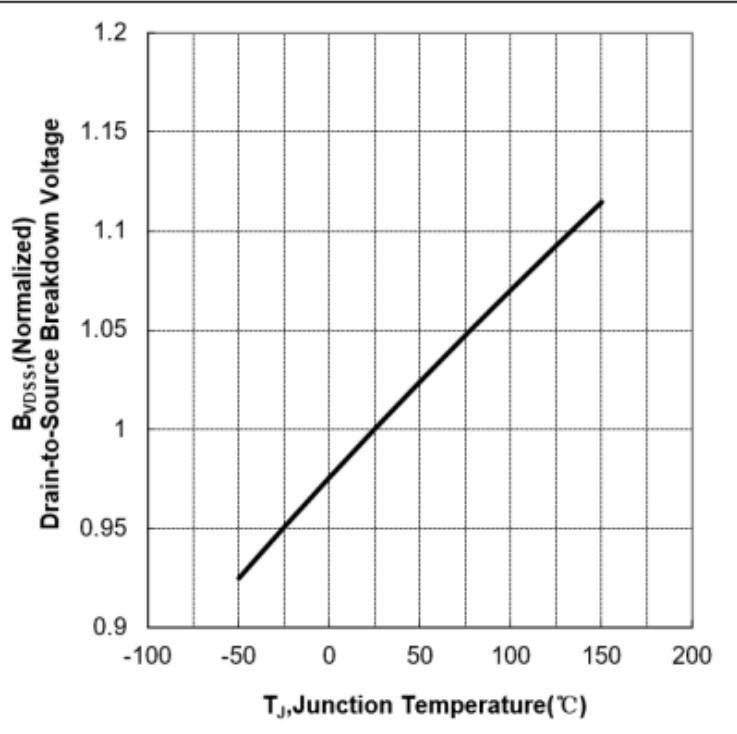


Figure 9 Typical Theshold Voltage vs Junction Temperature

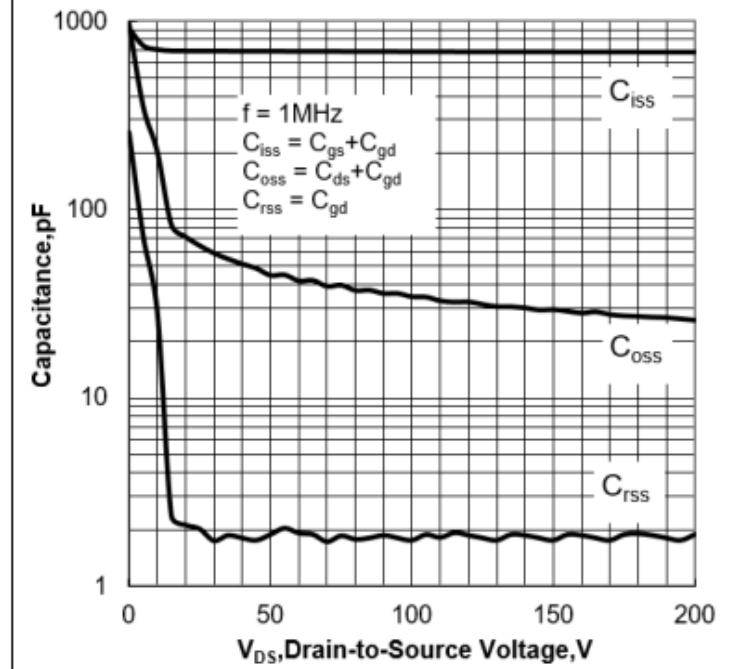
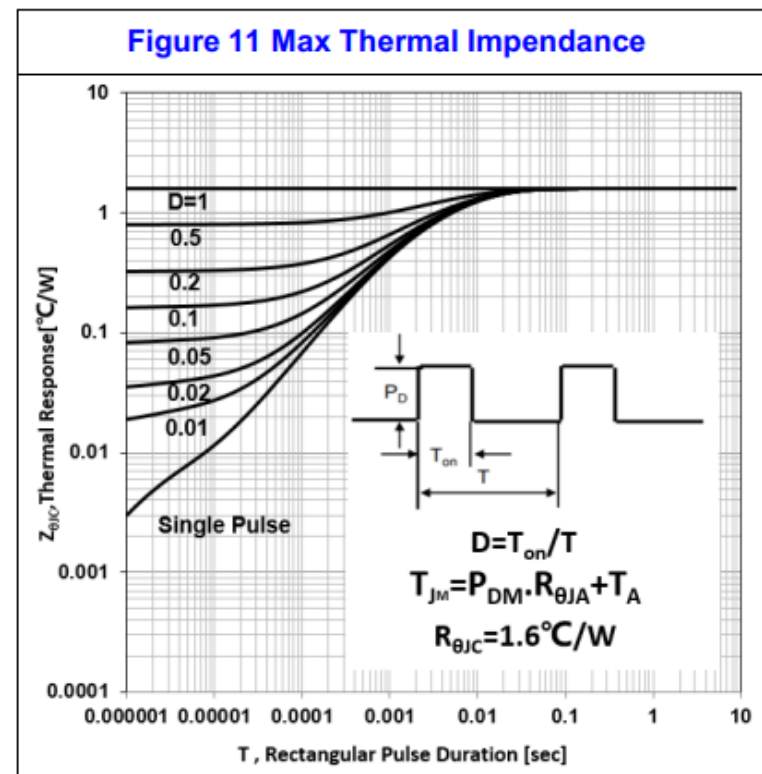
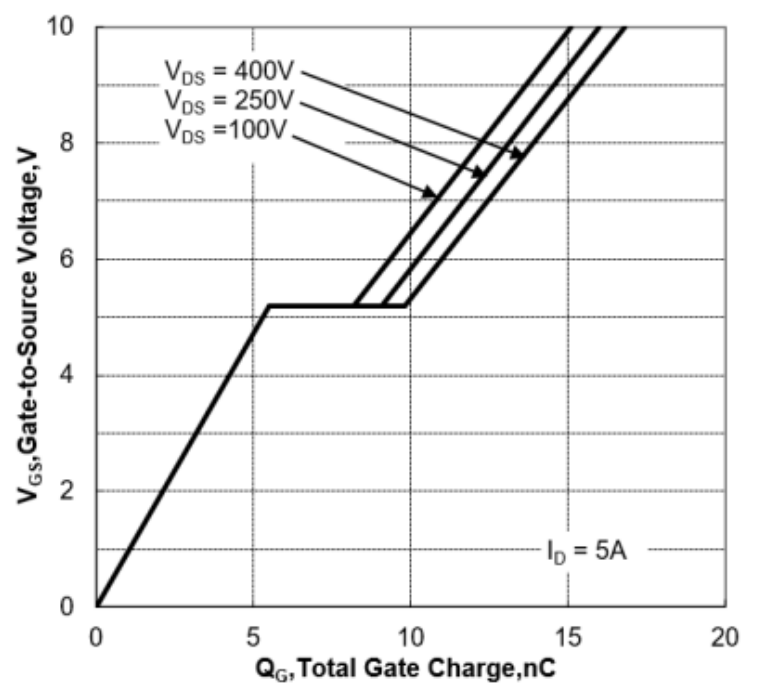
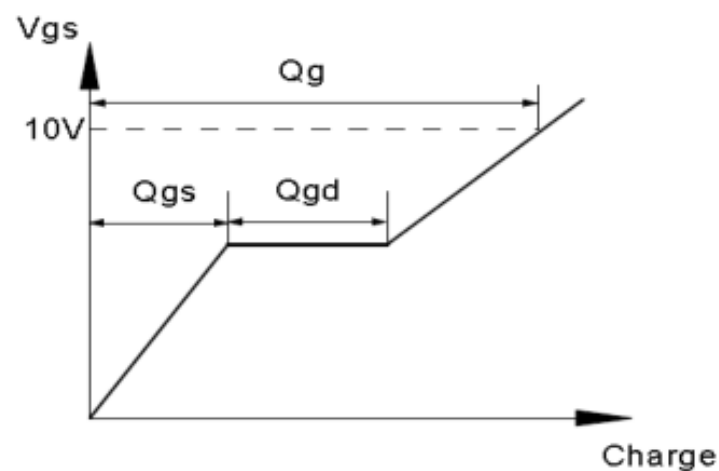
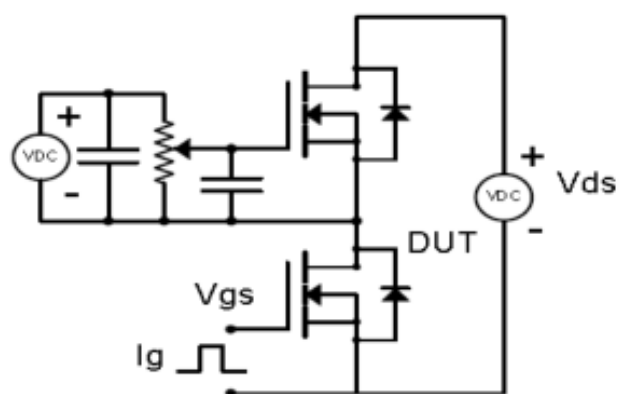


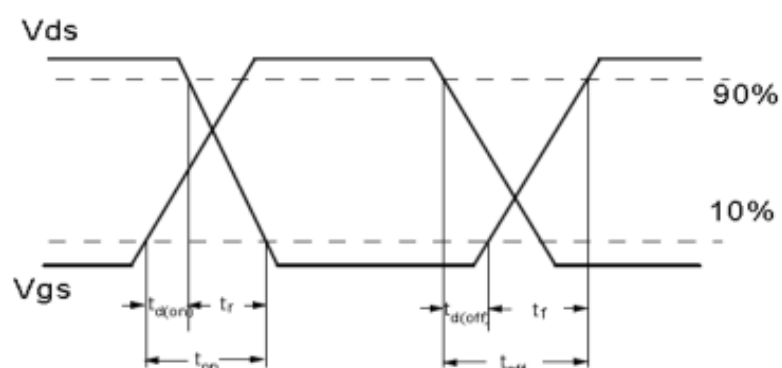
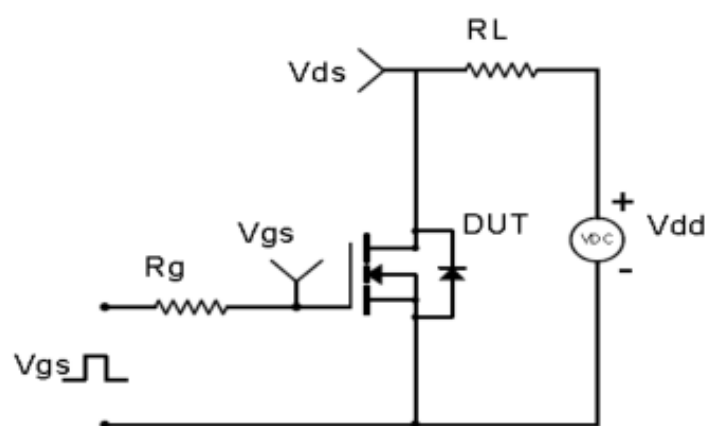
Figure 10 Typical Breakdown Voltage vs Junction Temperature



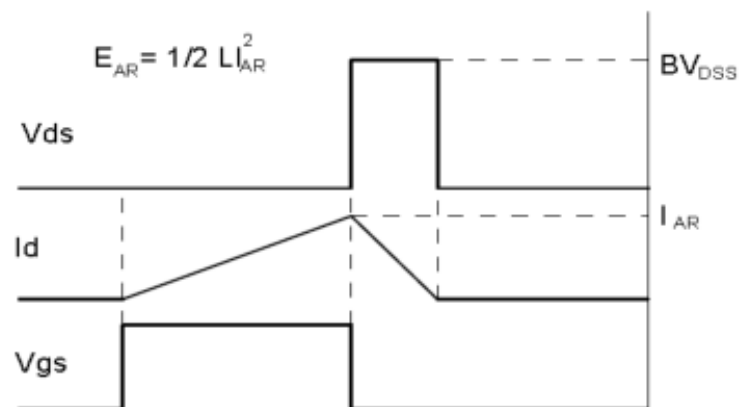
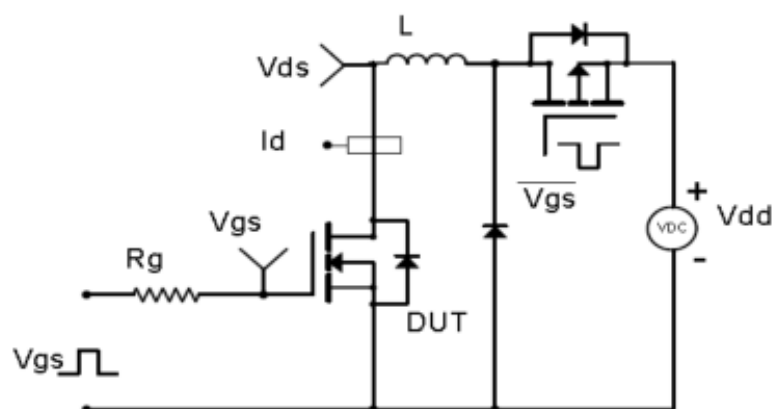
Gate Charge Test Circuit & Waveform



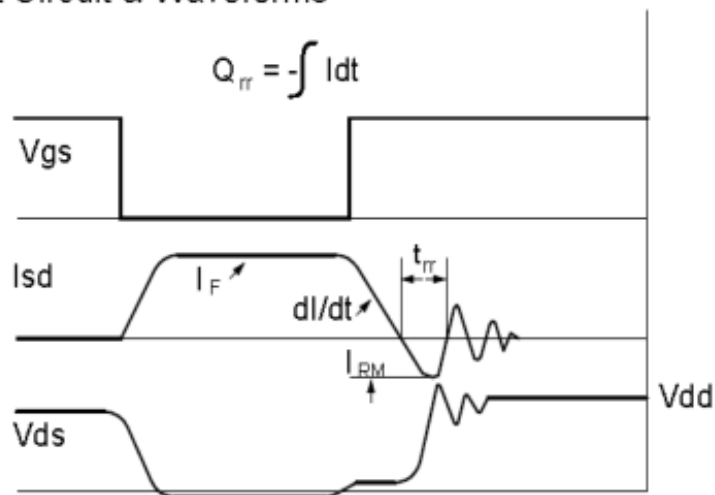
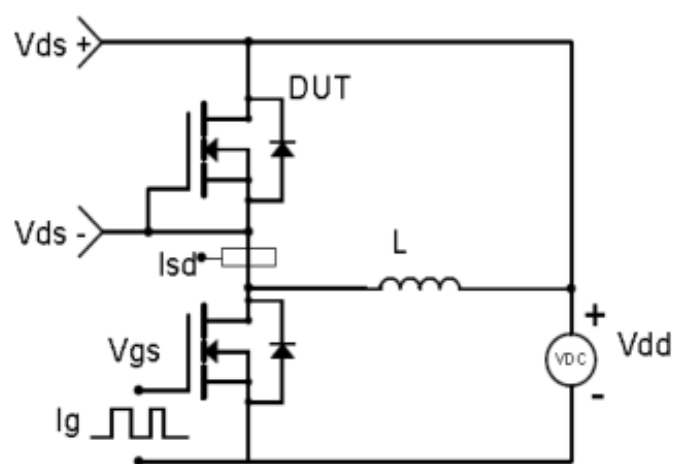
Resistive Switching Test Circuit & Waveforms



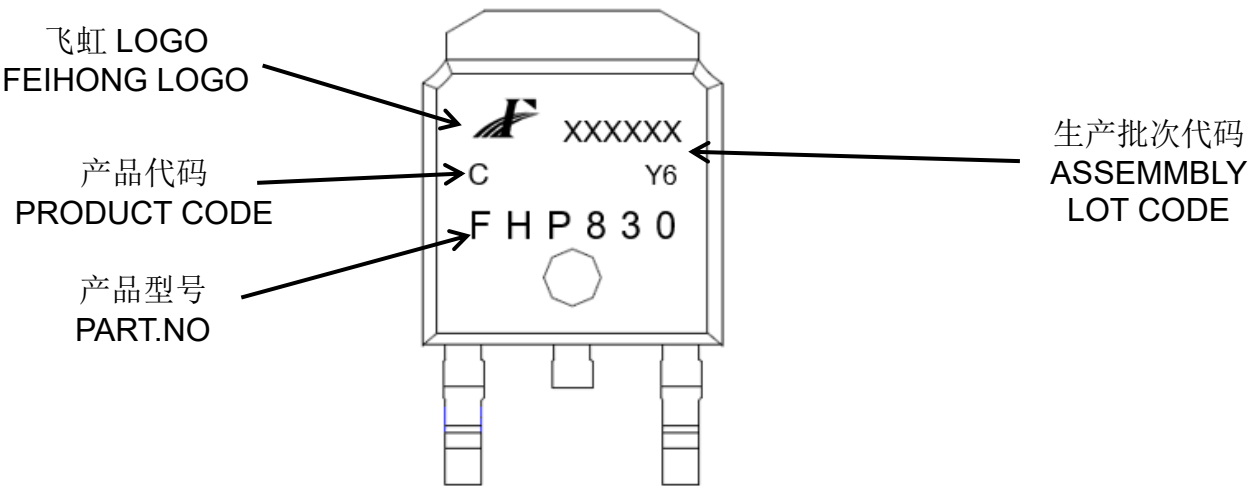
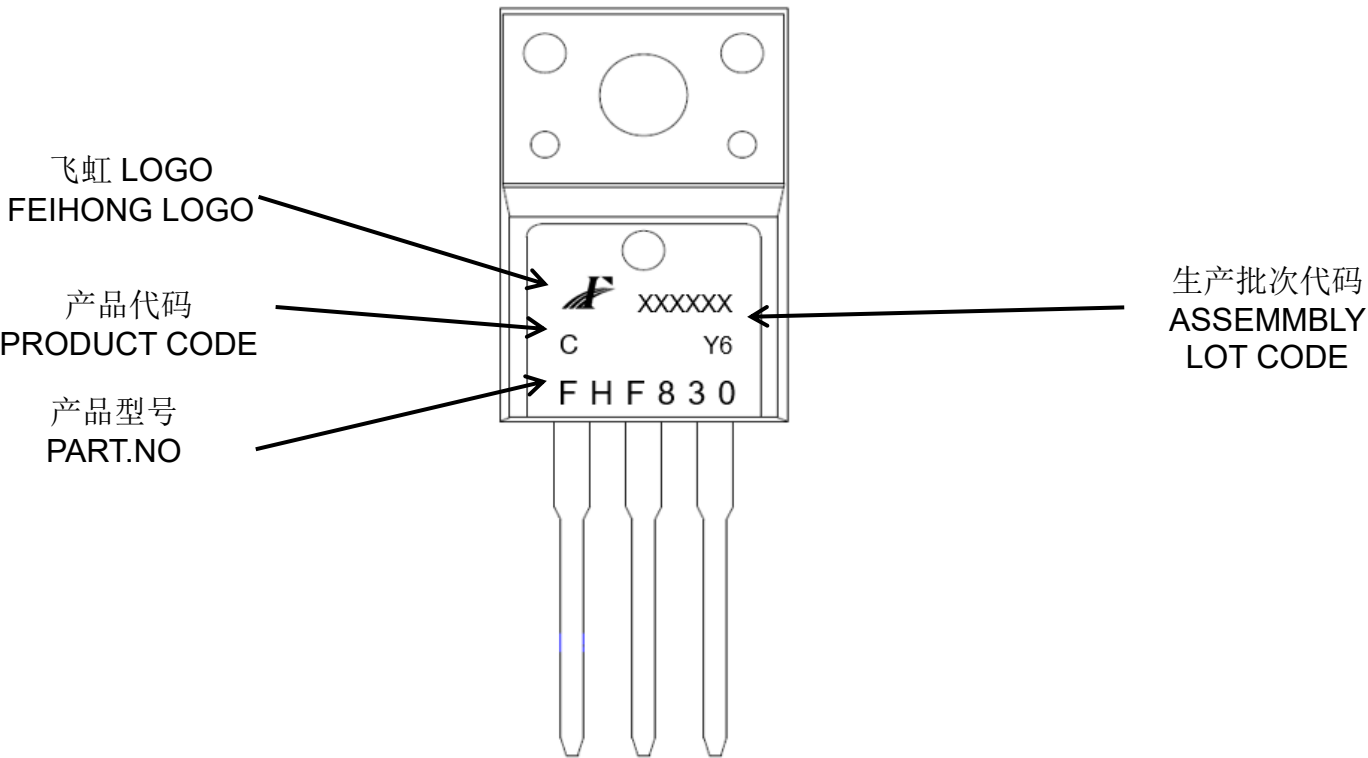
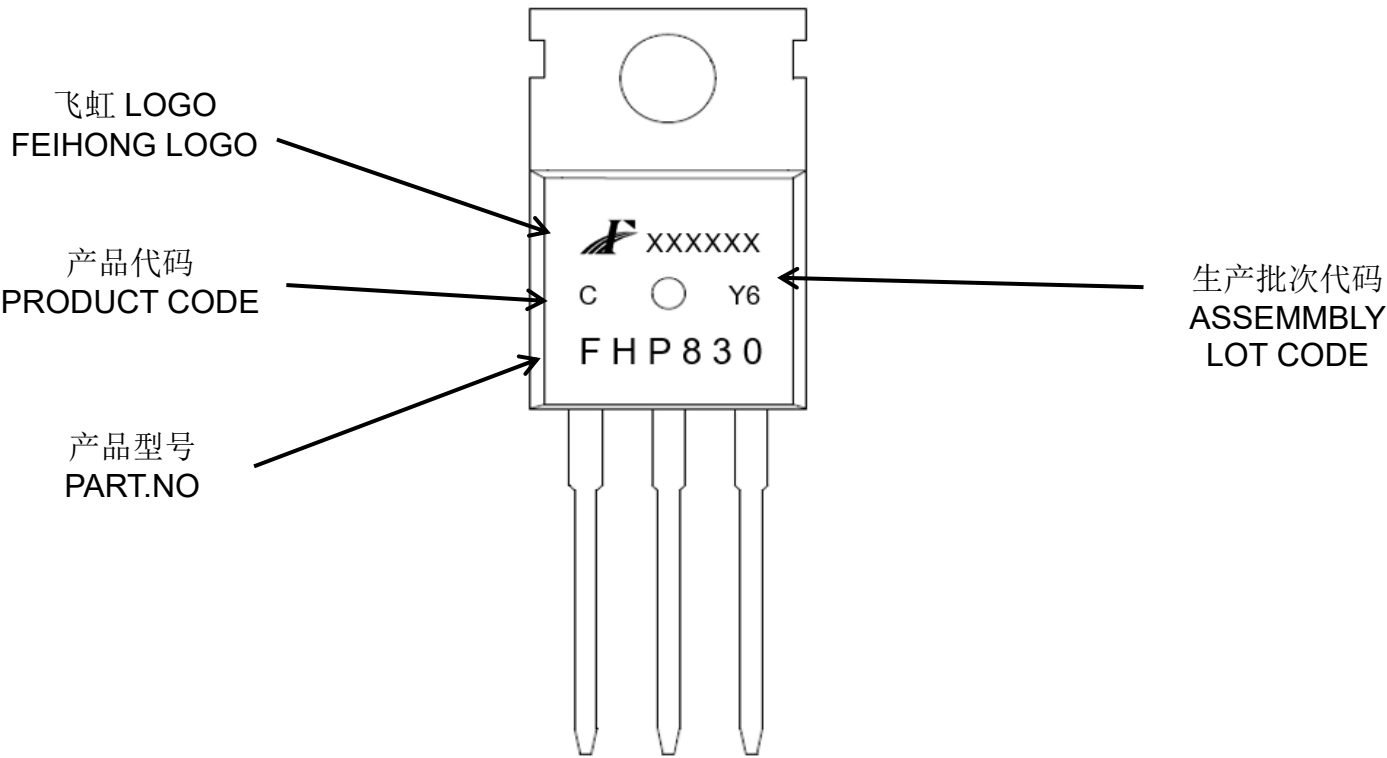
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



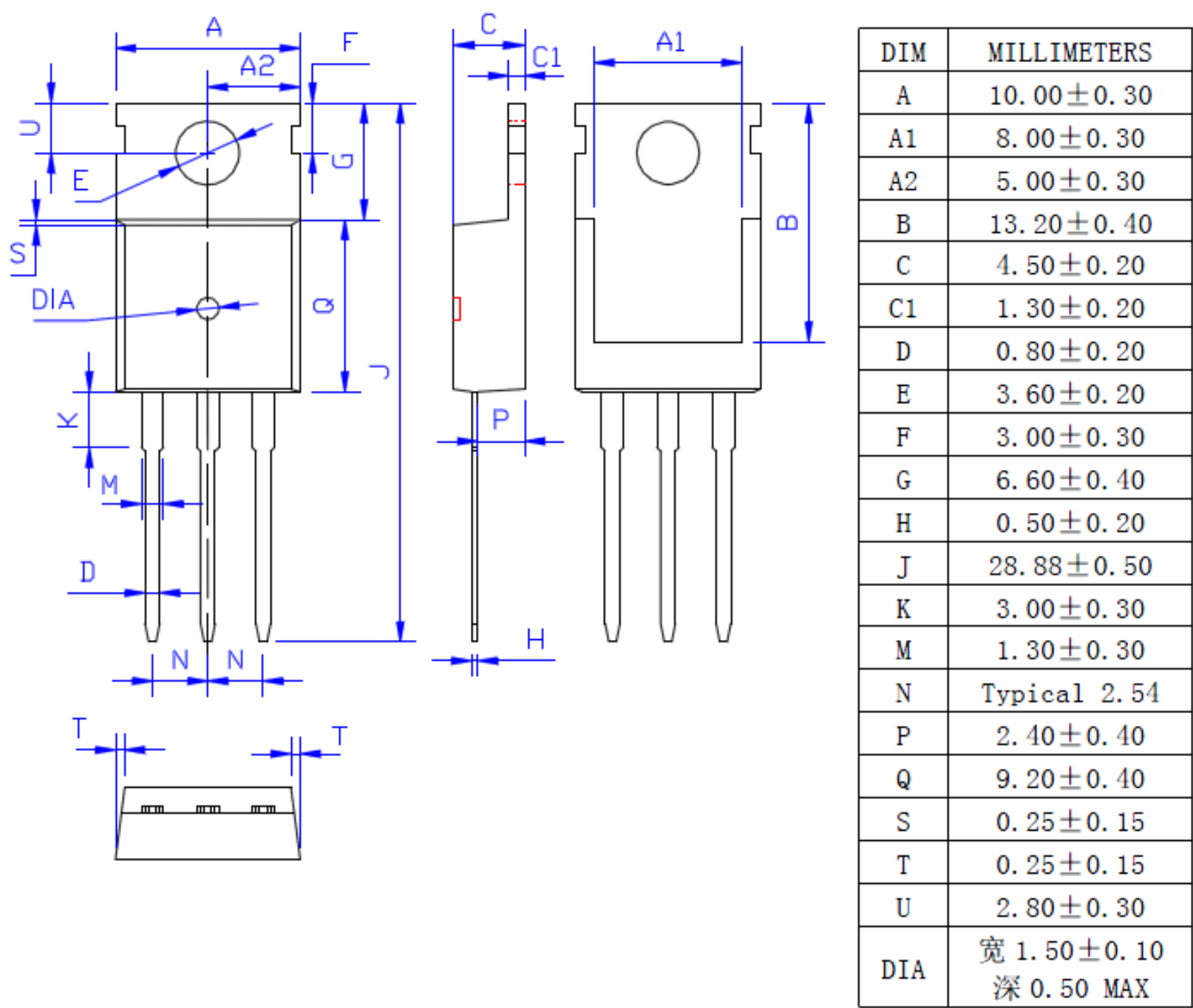
印记 Marking:



外形尺寸:

Package Dimension:

TO-220

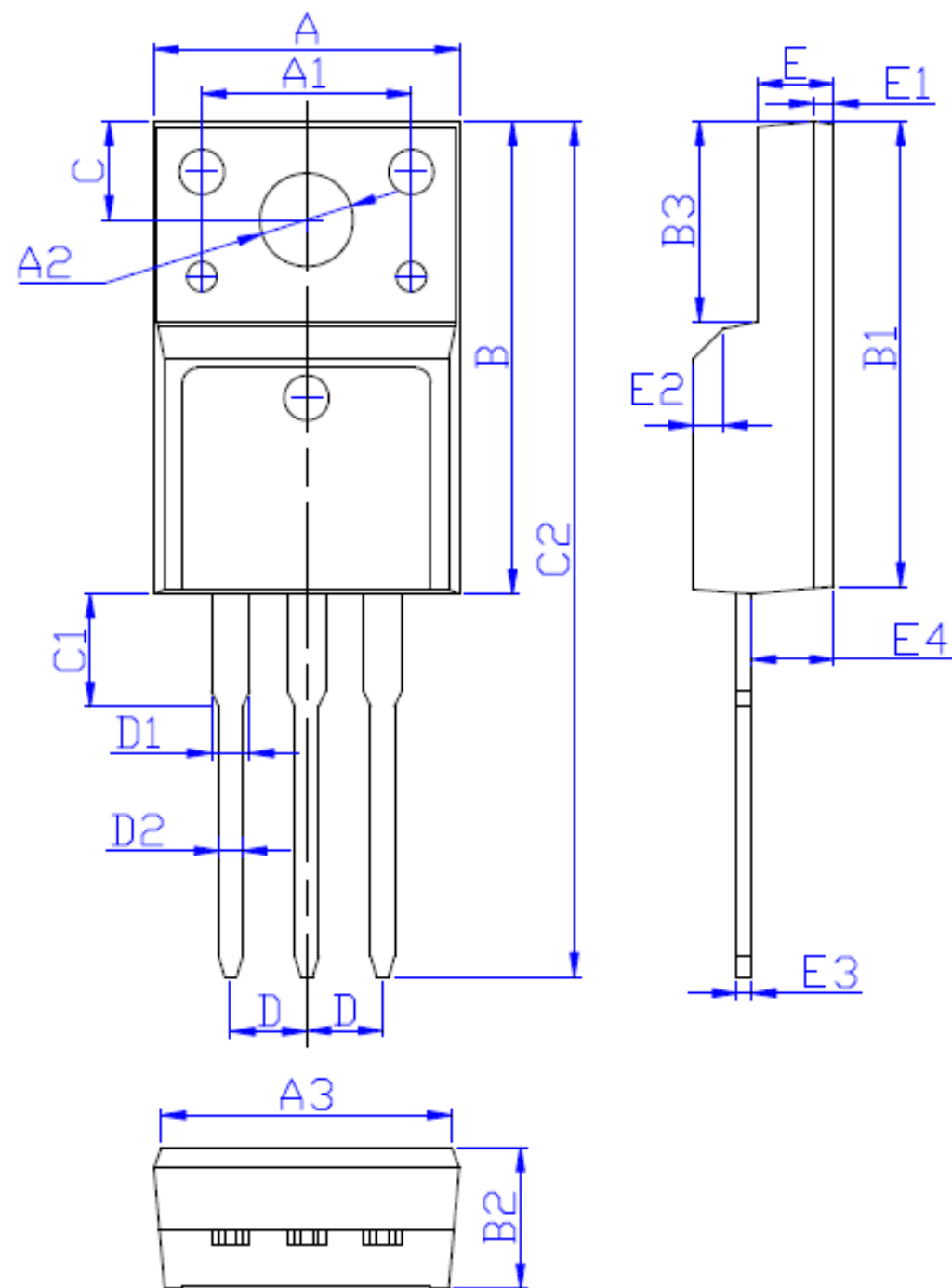


(Unit: mm)

外形尺寸:

Package Dimension:

TO-220F



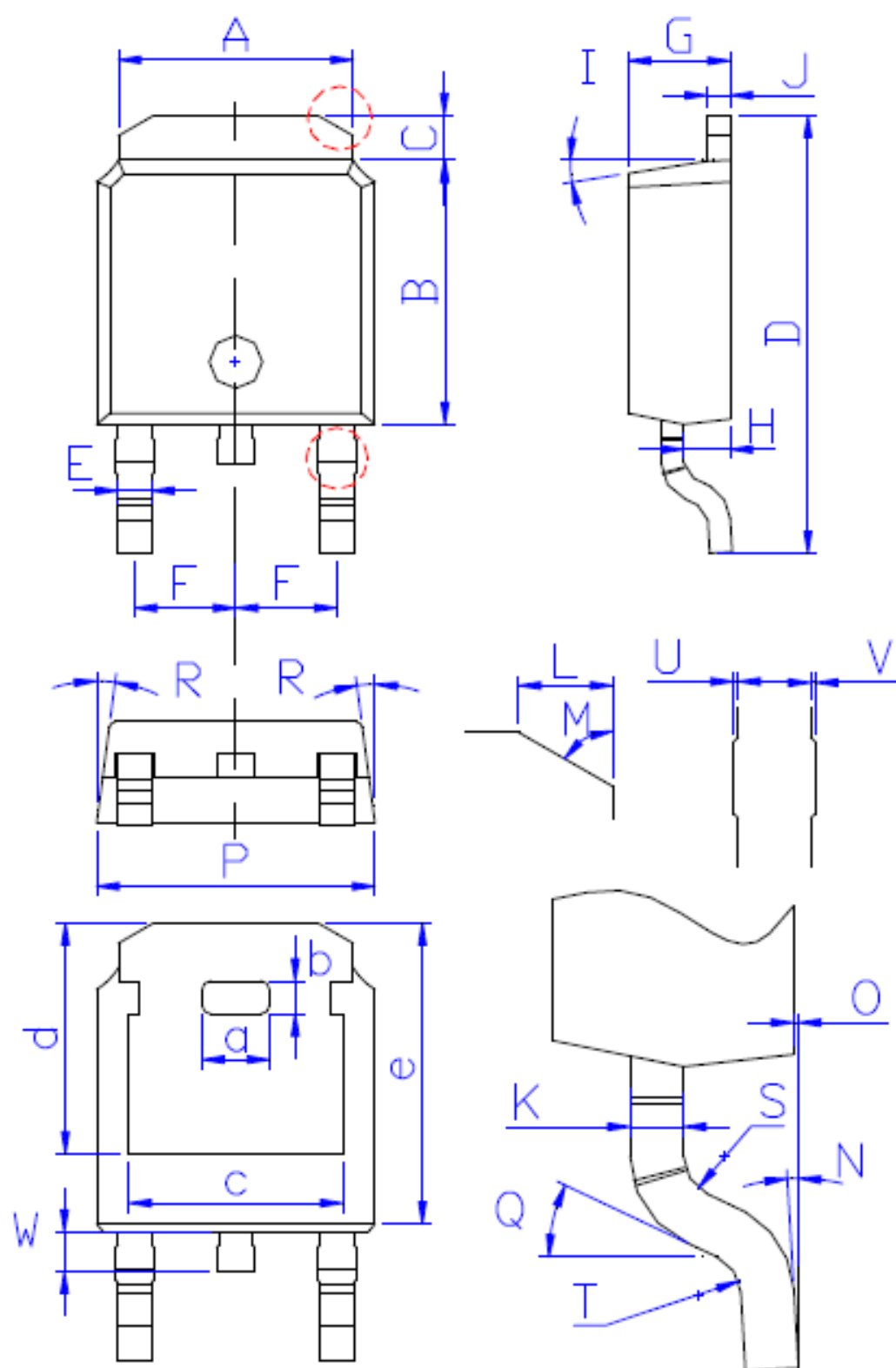
DIM	MILLIMETERS
A	10.16±0.30
A1	7.00±0.20
A2	3.12±0.20
A3	9.70±0.30
B	15.90±0.50
B1	15.60±0.50
B2	4.70±0.30
B3	6.70±0.30
C	3.30±0.25
C1	3.25±0.30
C2	28.70±0.50
D	Typical 2.54
D1	1.47 (MAX)
D2	0.80±0.20
E	2.55±0.25
E1	0.70±0.25
E2	1.0×45°
E3	0.50±0.20
E4	2.75±0.30

(Unit:mm)

外形尺寸:

Package Dimension:

TO-252



DIM	MILLIMETERS
A	5.34 ± 0.30
B	6.00 ± 0.30
C	1.05 ± 0.30
D	9.95 ± 0.30
E	0.76 ± 0.15
F	2.28 ± 0.15
G	2.30 ± 0.30
H	1.06 ± 0.30
I	$(4-10)^{\circ}$
J	0.51 ± 0.15
K	0.52 ± 0.15
L	0.80 ± 0.30
M	60°
N	$(0-10)^{\circ}$
O	0.05 ± 0.05
P	6.60 ± 0.30
Q	25°
R	$(4-8.5)^{\circ}$
S	R0.40
T	R0.40
U	0.05 ± 0.05
V	0.05 ± 0.05
W	0.90 ± 0.30
a	1.80 ± 0.30
b	0.75 ± 0.30
c	4.85 ± 0.30
d	5.30 ± 0.30
e	6.90 ± 0.30

(Units: mm)